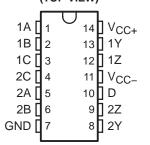
- Improved Stability Over Supply Voltage and Temperature Ranges
- Constant-Current Outputs
- High Speed
- Standard Supply Voltages
- High Output Impedance
- High Common-Mode Output Voltage Range
 ... –3 V to 10 V
- TTL-Input Compatibility
- Inhibitor Available for Driver Selection
- Glitch Free During Power Up/Power Down
- SN75112 and External Circuit Meets or Exceeds the Requirements of CCITT Recommendation V.35

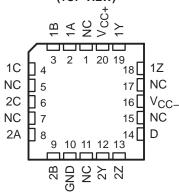
description/ordering information

The SN55110A, SN75110A, and SN75112 dual line drivers have improved output current regulation with supply-voltage and temperature variations. In addition, the higher current of the SN75112 (27 mA) allows data to be transmitted over longer lines. These drivers offer optimum performance when used with the SN55107A, SN75107A, and SN75108A line receivers.

SN55110A ... J OR W PACKAGE SN75110A ... D, N, OR NS PACKAGE SN75112 ... D OR N PACKAGE (TOP VIEW)



SN55110A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	DDID (N)	Tube of 25	SN75110AN	SN75110AN
0°C to 70°C	PDIP (N)	Tube of 25	SN75112N	SN75112N
		Tube of 50	SN75110AD	CNZE44OA
	COIC (D)	Reel of 2500	SN75110ADR	SN75110A
	SOIC (D)	Tube of 50	SN75112D	ON75440
		Reel of 2500	SN75112DR	SN75112
	SOP (NS)	Reel of 2000	SN75110ANSR	SN75110A
	ODID (I)	Tube of 05	SN55110AJ	SN55110AJ
–55°C to 125°C	CDIP (J)	Tube of 25	SNJ55110AJ	SNJ55110AJ
-55°C to 125°C	CFP (W)	Tube of 150	SNJ55110AW	SNJ55110AW
	LCCC (FK)	Tube of 55	SNJ55110AFK	SNJ55110AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SLLS106G - DECEMBER 1975 - REVISED NOVEMBER 2004

description/ordering information (continued)

These drivers feature independent channels with common voltage supply and ground terminals. The significant difference between the three drivers is in the output-current specification. The driver circuits feature a constant output current that is switched to either of two output terminals by the appropriate logic levels at the input terminals. The output current can be switched off (inhibited) by low logic levels on the enable inputs. The output current nominally is 12 mA for the '110A devices and is 27 mA for the SN75112.

The enable/inhibit feature is provided so the circuits can be used in party-line or data-bus applications. A strobe or inhibitor (enable D), common to both drivers, is included for increased driver-logic versatility. The output current in the inhibited mode, $I_{O(off)}$, is specified so that minimum line loading is induced when the driver is used in a party-line system with other drivers. The output impedance of the driver in the inhibited mode is very high. The output impedance of a transistor is biased to cutoff.

The driver outputs have a common-mode voltage range of –3 V to 10 V, allowing common-mode voltage on the line without affecting driver performance.

All inputs are diode clamped and are designed to satisfy TTL-system requirements. The inputs are tested at 2 V for high-logic-level input conditions and 0.8 V for low-logic-level input conditions. These tests ensure 400-mV noise margin when interfaced with TTL Series 54/74 devices.

The SN55110A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN75110A and SN75112 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each driver)

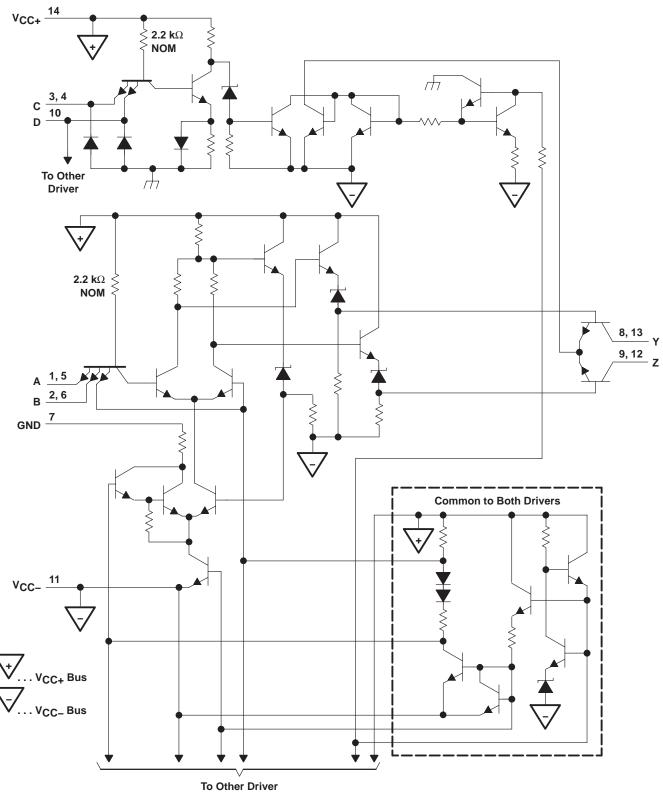
,											
LOGIC INPUTS			BLE UTS	оитритѕ†							
Α	В	С	D	Υ	Z						
Х	X	L	Х	Off	Off						
Χ	X	Χ	L	Off	Off						
L	X	Н	Н	On	Off						
Χ	L	Н	Н	On	Off						
Н	Н	Н	Н	Off	On						

H = high level, L = low level, X = irrelevant



[†] When using only one channel of the line drivers, the other channel should be inhibited and/or have its outputs grounded.

schematic (each driver)



Pin numbers shown are for the D, J, N, NS, and W packages.



SLLS106G - DECEMBER 1975 - REVISED NOVEMBER 2004

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

7 V
7 V
5.5 V
–5 V to 12 V
package 86°C/W
package 80°C/W
package 76°C/W
package 13.42°C/W
ackage 15.05°C/W
package 14.65°C/W
onds: J or W package 300°C
–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values are with respect to network ground terminal.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 4. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 5. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions (see Note 6)

		s	N55110 <i>A</i>	٨		SN75110A SN75112		
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} +	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{CC} -	Supply voltage	-4.5	-5	-5.5	-4.75	-5	-5.25	V
	Positive common-mode output voltage	0		10	0		10	V
	Negative common-mode output voltage	0		-3	0		-3	V
VIH	High-level input voltage	2			2			V
VIL	Low-level output voltage			0.8			0.8	V
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 6: When using only one channel of the line drivers, the other channel should be inhibited and/or have its outputs grounded.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMET	ER	TEST CON	DITIONS†	-	N55110 <i>A</i> N75110 <i>A</i>		,	SN75112		UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIK	Input clamp vo	oltage	$V_{CC\pm} = MIN,$	$I_L = -12 \text{ mA}$		-0.9	-1.5		-0.9	-1.5	V
			$V_{CC\pm} = MAX$,	V _O = 10 V		12	15		27	40	
I _{O(on)}	I _{O(on)} On-state output current		$V_{CC} = MIN \text{ to } M$ $V_{O} = -1 \text{ V to } 1 \text{ V}$					24	28	32	mA
			$V_{CC\pm} = MIN,$	$V_{O} = -3 V$	6.5	12		15	27		
IO(off)	Off-state outpo	ut current	$V_{CC\pm} = MIN$,	V _O = 10 V			100			100	μΑ
	Input current at maximum	A, B, or C inputs	V NAAV	V 55V			1			1	A
l ti	input voltage	D input	$V_{CC\pm} = MAX$,	$V_{ } = 5.5 \text{ V}$			2			2	mA
	High-level	A, B, or C inputs	V MAY	V 0.4V			40			40	
liH	input current	D input	$V_{CC\pm} = MAX$,	V _I = 2.4 V			80			80	μΑ
1	Low-level	A, B, or C inputs	V MAY	V 0.4 V			-3			-3	A
IIL	input current	D input	$V_{CC\pm} = MAX$,	V = 0.4 V			-6			-6	mA
ICC+(on)	Supply current from V _{CC}		V _{CC±} = MAX, A and B inputs a C and D inputs a	,		23	35		25	40	mA
I _{CC} -(on)	Supply current from V _{CC} _CC-(on) with driver enabled		V _{CC±} = MAX, A and B inputs a C and D inputs a	,		-34	-50		-65	-100	mA
ICC+(off)	Supply curren with driver inh		V _{CC±} = MAX, A, B, C, and D ir	nputs at 0.4 V		21			30		mA
I _{CC} -(off)	Supply curren with driver inh		$V_{CC\pm} = MAX$, A, B, C, and D in	nputs at 0.4 V		-17			-32		mA

[†] For conditions shown as MIN or MAX, use appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC\pm}$ = ± 5 V, T_A = 25°C (see Figure 1)

PARAMETER§	FROM (INPUT)	TO (OUTPUT)	TEST CO	MIN	TYP	MAX	UNIT	
t _{PLH}	A = = D	V 7	C: 40 mF	D: 500		9	15	
t _{PHL}	A or B	Y or Z	$C_L = 40 pF$,	$R_L = 50 \Omega$,		9	15	ns
t _{PLH}	C or D	Y or Z	C: - 40 pF	P. – 50 O		16	25	ns
t _{PHL}	COLD		$C_L = 40 \text{ pF},$	$R_L = 50 \Omega$,		13	25	115

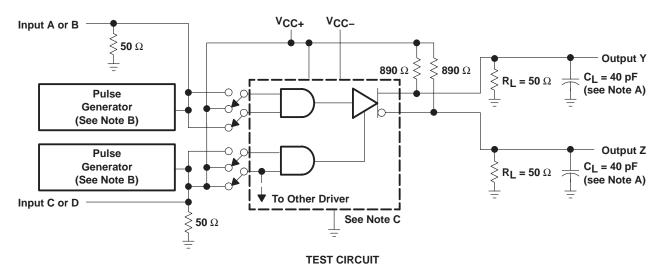
 $[\]S$ tpLH = propagation delay time, low- to high-level output

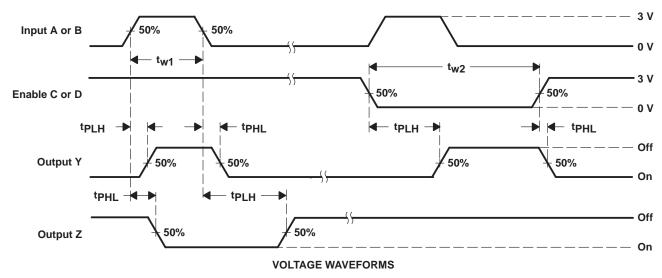


[‡] All typical values are at $V_{CC+} = 5 \text{ V}$, $V_{CC-} = -5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 $t_{\mbox{\footnotesize{PHL}}}$ = propagation delay time, high- to low-level output

PARAMETER MEASUREMENT INFORMATION



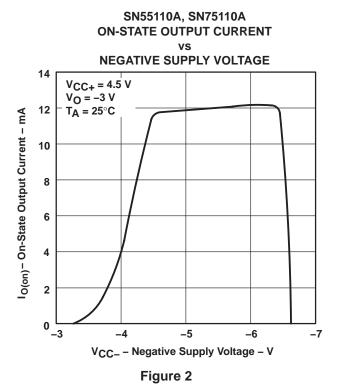


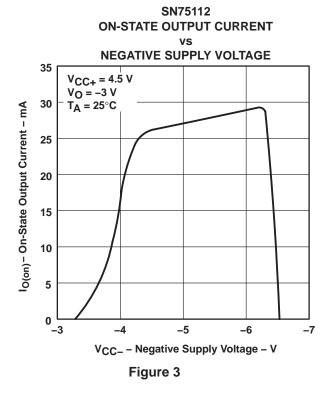
NOTES: A. C_I includes probe and jig capacitance.

- B. The pulse generators have the following characteristics: $Z_O = 50 \ \Omega$, $t_\Gamma = t_f = 10 \pm 5$ ns, $t_{W1} = 500$ ns, PRR \leq 1 MHz, $t_{W2} = 1 \ \mu s$, PRR \leq 500 kHz.
- C. For simplicity, only one channel and the enable connections are shown.

Figure 1. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS





APPLICATION INFORMATION

special pulse-control circuit

Figure 4 shows a circuit that can be used as a pulse-generator output or in many other testing applications.

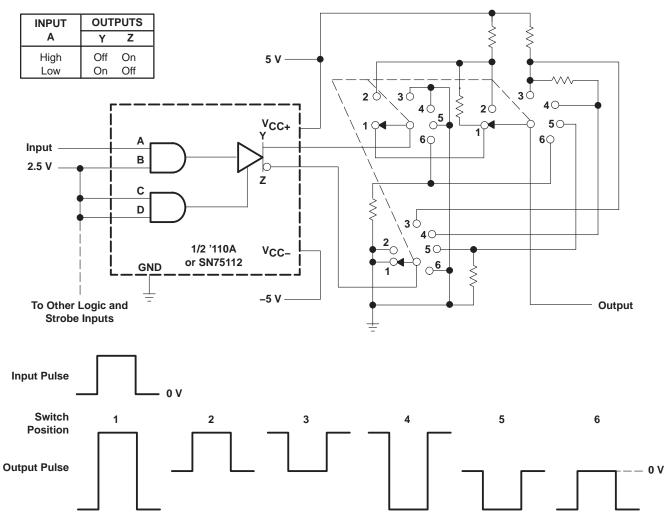


Figure 4. Pulse-Control Circuit

APPLICATION INFORMATION

using the SN75112 as a CCITT-recommended V.35 line driver

The SN75112 dual line driver, the SN75107A dual line receiver, and some external resistors can be used to implement the data-interchange circuit of CCITT recommendation V.35 (1976) modem specification. The circuit of one channel is shown in Figure 5 and meets the requirement of the interface as specified by Appendix 11 of CCITT V.35 and is summarized in Table 1 (V.35 has been replaced by ITU V.11).

		•	
GENERATOR	MIN	MAX	UNIT
Source impedance, Z _{Source}	50	150	Ω
Resistance to ground, R	135	165	Ω
Differential output voltage, VOD	440	660	mV
10% to 90% rise time, t _r	40		ns
or		$0.01 \times ui^{\dagger}$	
Common-mode output voltage, VOC	-0.6	0.6	V
LOAD (RECEIVER)	MIN	MAX	UNIT
Input impedance, Z _I	90	110	Ω
Resistance to ground, R	135	165	Ω

Table 1. CCITT V.35 Electrical Requirements

[†] ui = unit interval or minimum signal-element pulse duration

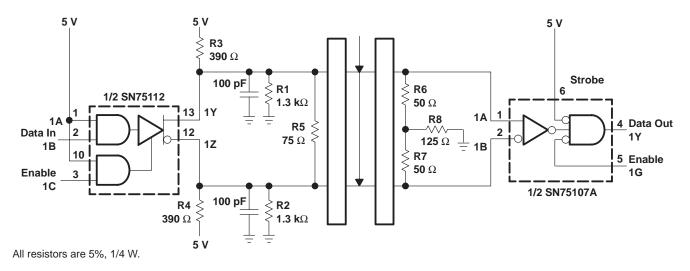


Figure 5. CCITT-Recommended V.35 Interface Using the SN75112 and SN75107A

22-Jan-2025

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87547012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87547012A SNJ55 110AFK	Samples
5962-8754701CA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8754701CA SNJ55110AJ	Samples
5962-8754701DA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8754701DA SNJ55110AW	Samples
SN55110AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN55110AJ	Samples
SN75110AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75110A	Samples
SN75110ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75110A	Samples
SN75110AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75110AN	Samples
SN75110ANSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75110A	Samples
SN75112D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75112	Samples
SN75112DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75112	Samples
SN75112N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75112N	Samples
SNJ55110AFK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87547012A SNJ55 110AFK	Samples
SNJ55110AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8754701CA SNJ55110AJ	Samples
SNJ55110AW	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8754701DA SNJ55110AW	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PACKAGE OPTION ADDENDUM

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PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN55110A, SN75110A:

Catalog: SN75110A

Military: SN55110A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75110ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75110ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75110ANSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75112DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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*All dimensions are nominal

7 III GIITTOTTOTOTTO GITO TTOTTIITIGI							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75110ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN75110ADR	SOIC	D	14	2500	340.5	336.1	32.0
SN75110ANSR	SOP	NS	14	2000	356.0	356.0	35.0
SN75112DR	SOIC	D	14	2500	356.0	356.0	35.0



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-87547012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8754701DA	W	CFP	14	25	506.98	26.16	6220	NA
SN75110AD	D	SOIC	14	50	506.6	8	3940	4.32
SN75110AN	N	PDIP	14	25	506	13.97	11230	4.32
SN75110AN	N	PDIP	14	25	506	13.97	11230	4.32
SN75112D	D	SOIC	14	50	506.6	8	3940	4.32
SN75112N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ55110AFK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ55110AW	W	CFP	14	25	506.98	26.16	6220	NA



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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